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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Wing-Cheong Gilbert Lai et al. 09/282441	
	Filing Date: Herewith	Group: Unknown

## U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
TU	4,999,160	03/12/1991	Lowrey, T.A., et al.	420	529	12/04/88
	5,192,589	03/09/1993	Sandhu, G.S.	427	255.1	09/05/91
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**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes   No
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## OTHER DOCUMENTS

**Examiner Initial	Including Author, Title, Date, Pertinent Pages, Etc.
TU	Fiordalice, R.W., et al., "Orientation Control of Chemical Vapor Deposition TiN Film for Barrier Applications", <u>Journal of the Electrochemical Society</u> , 143(6), pgs. 2059-2063, (June 1996)
TU	Lee, H., et al., "Study of Diffusion Barrier Performance in MOCVD TiN by Transmission Electron Microscopy", <u>Materials Research Society Symposium Proceedings</u> , 391, pgs. 205-209, (1995)
TU	Pramanik, D., et al., "Effect of Underlayer on Sputtered Aluminum Grain Structure and its Correlation with Step Coverage in Submicron Vias", 1990 <u>Proceedings Seventh International IEEE VLSI Multilevel Interconnection Conference</u> , IEEE Catalog No. 90TH0325-1, pgs. 332 - 334, (June 1990)

Examiner	Guay	Date Considered	6/13/03
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\*Substitute Disclosure Statement Form PTO 1449

\*\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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